



## **IDT Orders Applied Materials' NanoSEM 3D Metrology System**

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### ***IDT Uses Complete Suite of Applied Materials' Metrology and Wafer Inspection Systems To Provide High Yield On Advanced Communications Chips***

Applied Materials, Inc. announced that Integrated Device Technology (IDT), a manufacturer of advanced communications chips, has purchased a NanoSEM 3D(TM) system, the industry's only fully automated 3D CD-SEM.\* IDT plans to use the NanoSEM 3D to provide the precise dimensional control required for its latest generation of chips. This latest purchase completes the IDT suite of Applied Materials' metrology and inspection technologies, which has replaced established competitive systems for all applications.

"We have purchased Applied Materials' systems for our critical wafer inspection, CD-SEM and defect review SEM requirements based on the company's depth of process and defect knowledge, and the demonstrated advantages in system technology and productivity," said Mike Hunter, vice president of worldwide manufacturing for IDT. "We've recently selected the NanoSEM 3D system because it has demonstrated a range of unique capabilities that significantly enhance our control of the critical lithography and etch processes that are so important to device yield and fab profitability."

For CD-SEM metrology, the NanoSEM 3D system features unique imaging technology that allows customers to automatically view and measure both the top and sides of chip features and rapidly capture excursions invisible to conventional top-view CD metrology tools. By helping define and control the lithography and etch process window, the NanoSEM 3D system lets users automatically monitor critical parameters such as stepper focus and etch depth, contributing to increased device yield and fab profitability.

IDT also utilizes Applied Materials' CompassPro(TM) system for wafer inspection of critical defects, and the SEMVision(TM) G2 for defect review, which analyzes defects and finds their root causes. Using the CompassPro and the SEMVision defect review systems together, combined with Applied Materials' in-depth process expertise and process integration knowledge, IDT can significantly reduce the time spent optimizing inspection recipes for many different inspection steps and accelerate the ramping of new generations of chip production.

"IDT has a broad product portfolio with multiple device types that requires a high degree of manufacturing flexibility and automation, which is a perfect fit for our inspection and metrology technologies," said Dr. Gilad Almogy, vice president and general manager of Applied Materials' Process Diagnostics and Control division. "Having our full set of systems in their fab gives us an opportunity to fully integrate our extensive defect knowledge with the IDT installed base of Applied Materials' deposition, etch, RTP\* and CMP\* systems in a way that provides exceptional value and productivity in both current production and future development settings."

Applied Materials (Nasdaq: AMAT), the largest supplier of products and services to the global semiconductor industry, is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone(TM) by helping semiconductor manufacturers produce more powerful, portable and affordable chips. Applied Materials' Web site is <http://www.appliedmaterials.com>

\*CD-SEM = Critical Dimension Scanning Electron Microscope \*CMP = Chemical Mechanical Polishing \*RTP = Rapid Thermal Processing

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